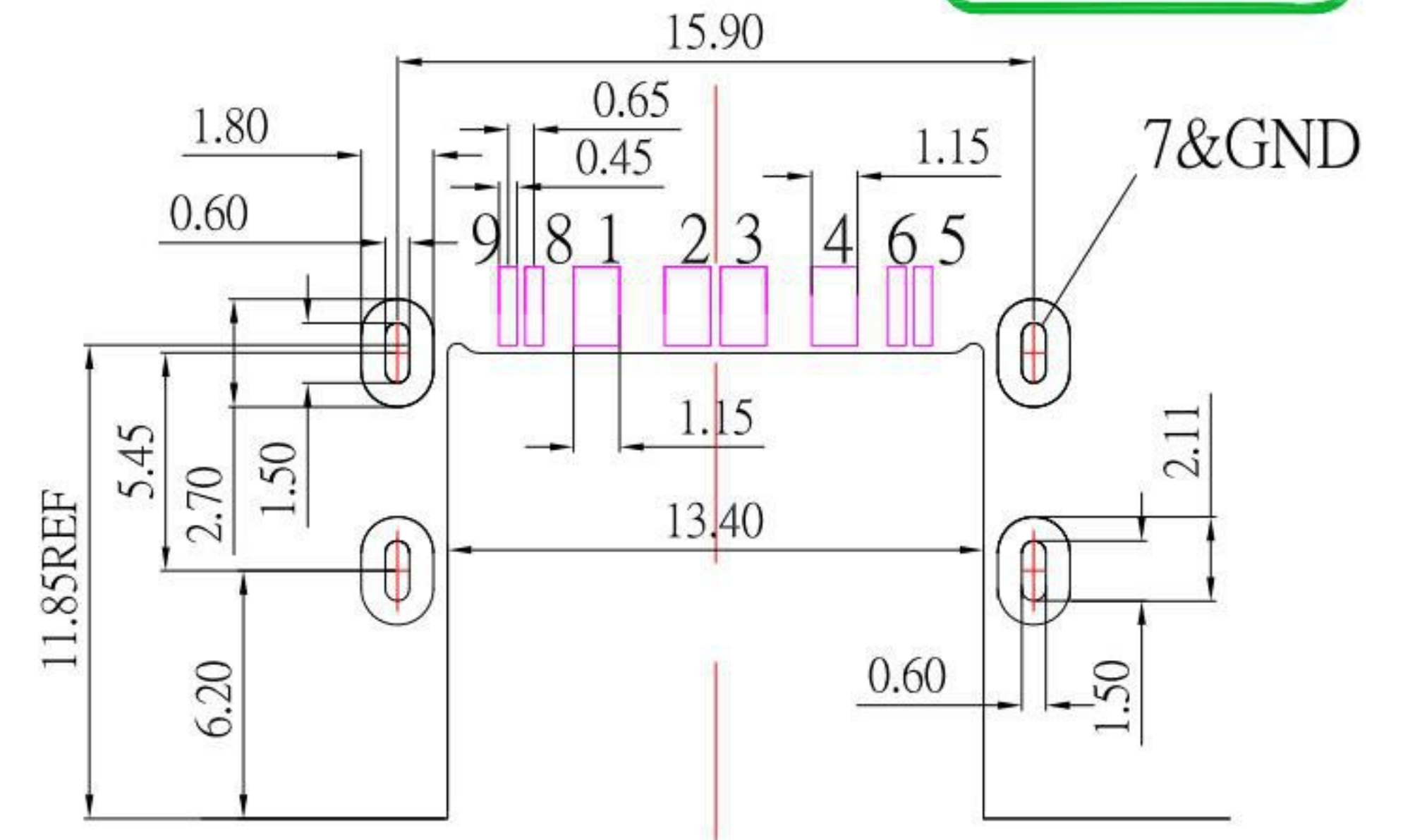
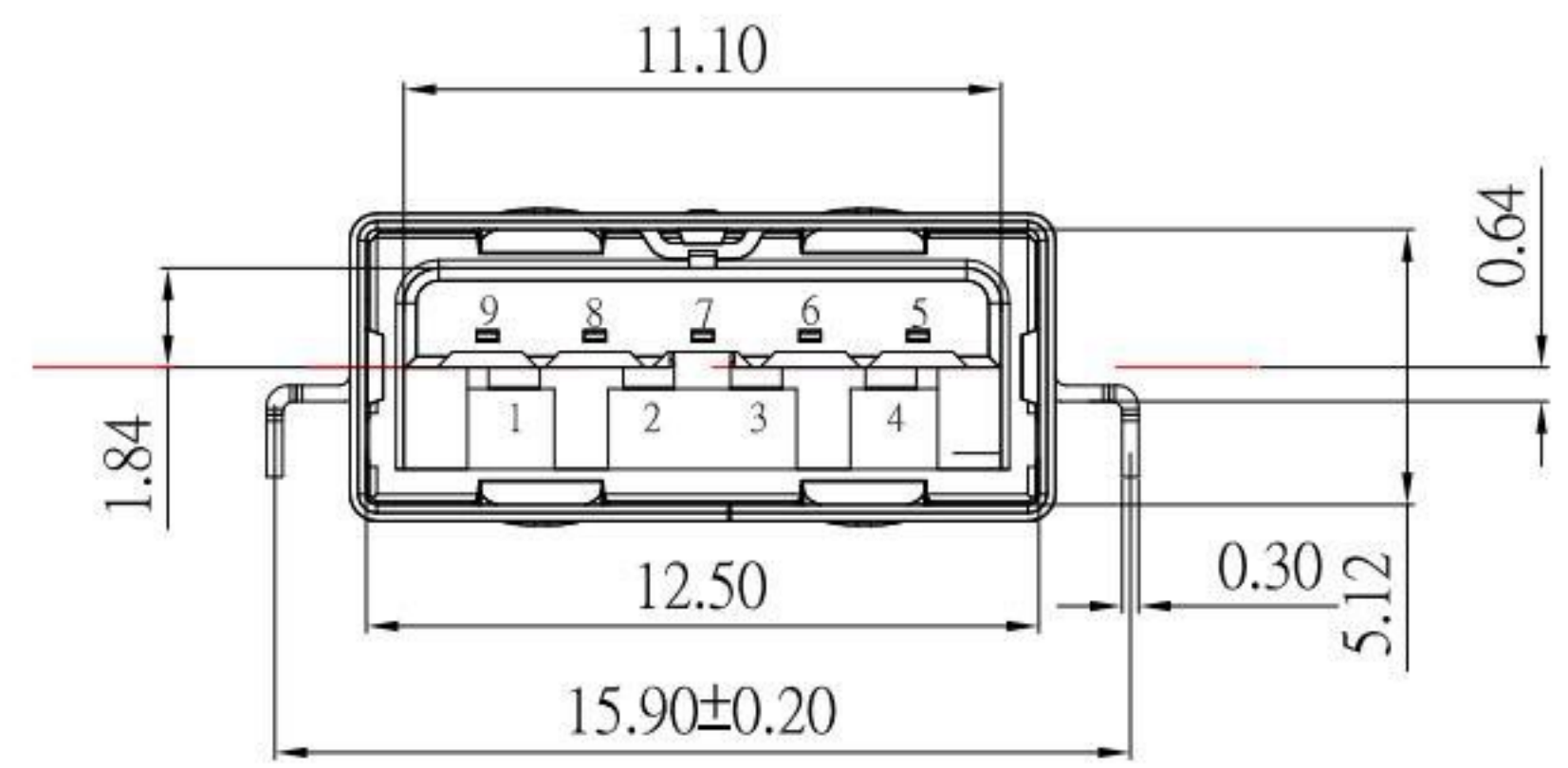
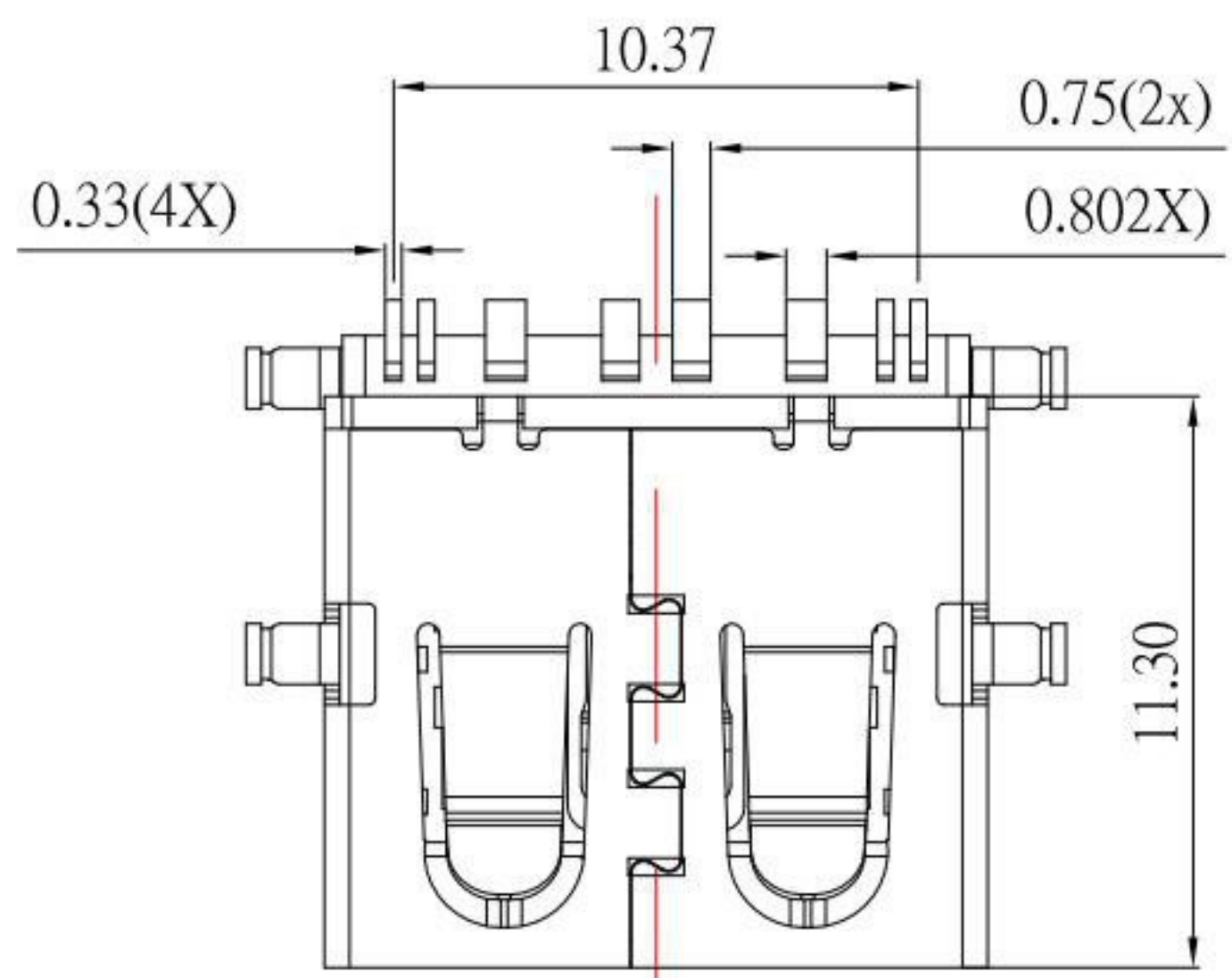
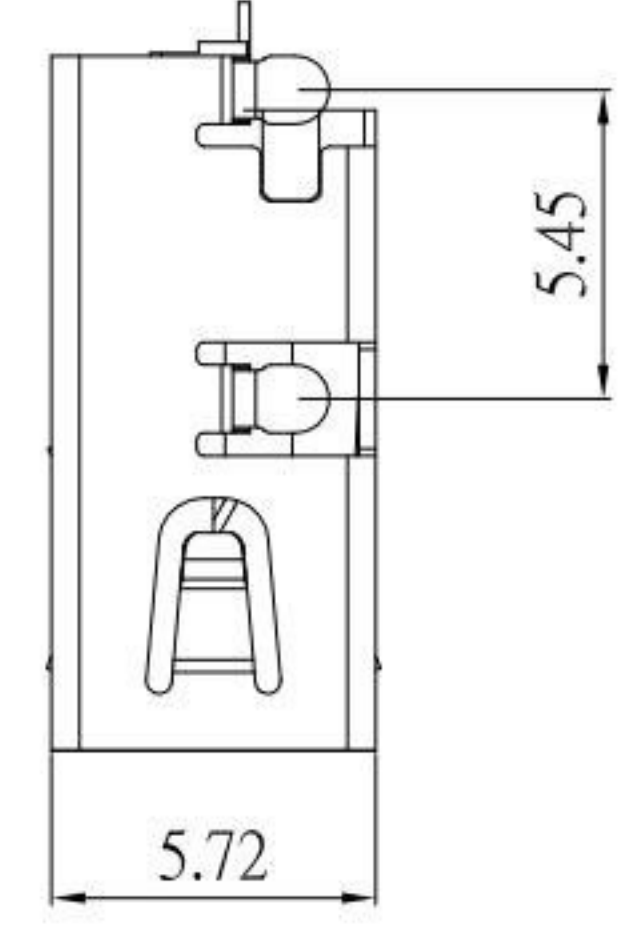
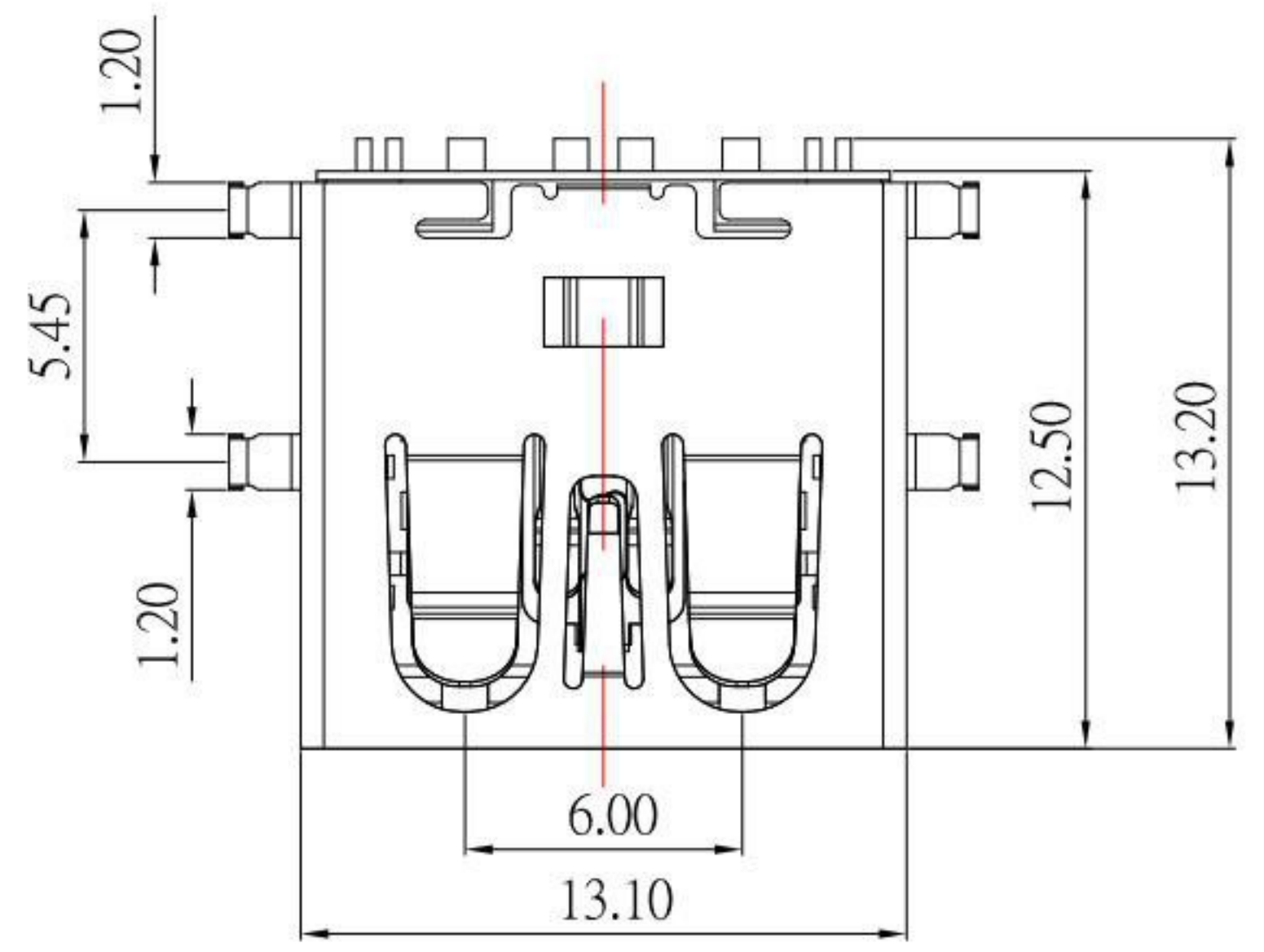
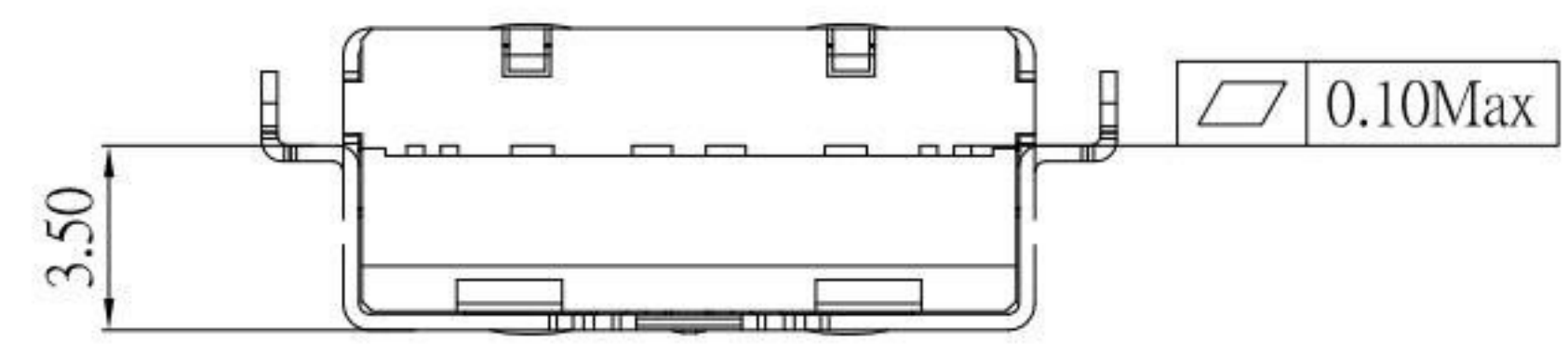




# SUA-110E16-32x-S242

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



## RECOMMENDED PCB LAYOUT

NOTE:

- 1.MATERIAL:
  - 1.1 Housing: LCP
  - 1.2 Contact: Phosphor Bronze
  - 1.3 Shell: SUS
- 2.Finish:
  - 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
  - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
  - 3.1 Rate: 3.0 A
  - 3.2 insulator Resistance:1000MΩ Min
  - 3.3 Dielectric Strength: 500V AC
  - 3.4 Contact Resistance: 30mΩ Max
  - 3.5 Operation Temperature: -25°C ~ +85°C
  - 3.6 Insertion Force: 35 N
  - 3.7 Extraction Force: 10 N

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

**KSD** 科斯达电子科技有限公司  
 SWITCH CONNECTOR KSD ELECTRONIC TECHNOLOGY Co., LTD  
 全球 互联零组件制造企业

TOLERANCE UNLESS OTHERWISE STATED:	Up to 5 ±0.2	5 ~ 15 ±0.3	15 ~ 30 ±0.4	30 ~ 50 ±0.5	Angle ±0.3°
	3RD. ANGEL'S	UNITS	MM		

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/13/21		MODLE	USB AF 3.0 沉板 板上H3.50mm 無捲邊 GEN 2
CHECKED BY:	DATE	FINISH	DWG NO.	SUA-110E16-32x-S242
Jacky Chen	05/13/21		PART NO.	SUA-110E16-32x-S242
APPROVED BY:	DATE	SCALE	SHEET NO.	1 of 1
Tony Kao	05/13/21	1 : 1		

ITEM NO.	DESCRIPTION	DRAWN	DATE